**Newsletter**

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**April 2024**

- Kaufman Call for Nominations
- TCASAI Announcement
- ICCAD Call for Papers
- IEEE Education Week
- ESL Update
- D&T Special Issue CFP
- SSH-SOC 2024
- SMACD 2024
- MLCAD 2024
- MEMOCODE 2024
- SIES 2024

**CONFERENCES**    **PUBLICATIONS**

**ANNOUNCEMENTS**    **CALLBOARD**

**KAUFMAN AWARD**

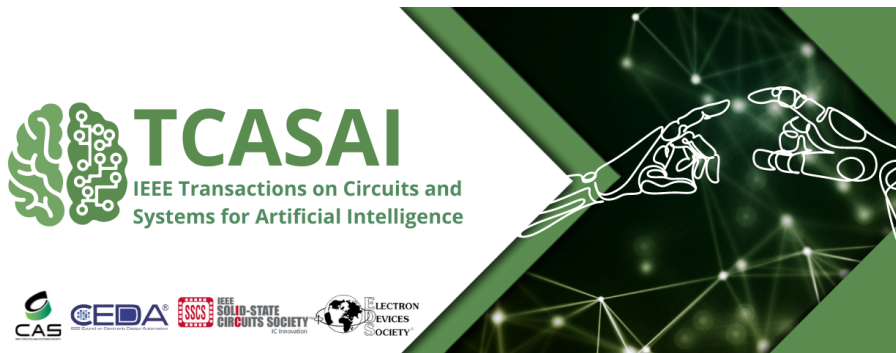Call for Nominations

Due 30 JUNE 2024

# Phil Kaufman Award

**Nomination Deadline:** 30 June 2024

The **Phil Kaufman Award** honors individuals who have made a demonstrable impact on the field of electronic system design through technology innovations, education/mentoring, or business or industry leadership.

**Prize and Presentation:** The award will be presented at a dinner and ceremony honoring the recipient to be held in Silicon Valley. The recipient's name will be listed on a permanent large award and a smaller individual award will be presented to the recipient. Hotel and airline expenses of the recipient and spouse/partner will be included.

**Submit a Nomination**



## IEEE Transactions on Circuits and Systems for Artificial Intelligence (TCASAI)

We are excited to announce the launch of the IEEE Transactions on Circuits and Systems for Artificial Intelligence (TCASAI), the latest addition to the IEEE's esteemed collection of scholarly publications. TCASAI publishes contributions related to circuits and systems for artificial intelligence, including circuit and electronic system design, implementation, and demonstration. This new Transactions aims to offer a timely and important venue to fulfill the strong need of the IEEE communities in publishing research and technical contributions in this fast-growing field.

TCASAI is financially sponsored by the IEEE Circuits and Systems Society (CASS), IEEE Solid-State Circuits Society (SSCS), and the IEEE Council on Electronic Design Automation (CEDA), and technically sponsored by the IEEE Electron Devices Society (EDS).

The submission portal of TCASAI will be announced soon.

**Learn More**

**CALL FOR PAPERS!**

Submission Deadline:
May 5, 2024

SUBMIT TODAY

## International Conference on Computer-Aided Design (ICCAD 2024)

**27-31 October 2024 | New Jersey, USA**

The International Conference on Computer-Aided Design focuses on advancements and research in the field of electronic design automation (EDA) and computer-aided design (CAD) for integrated circuits and systems.

**Abstracts Due: 28 April 2024**
**Papers Due: 5 May 2024**

Topics:

- System-Level CAD
- Synthesis, Verification, Physical Design, Analysis, Simulation, and Modeling
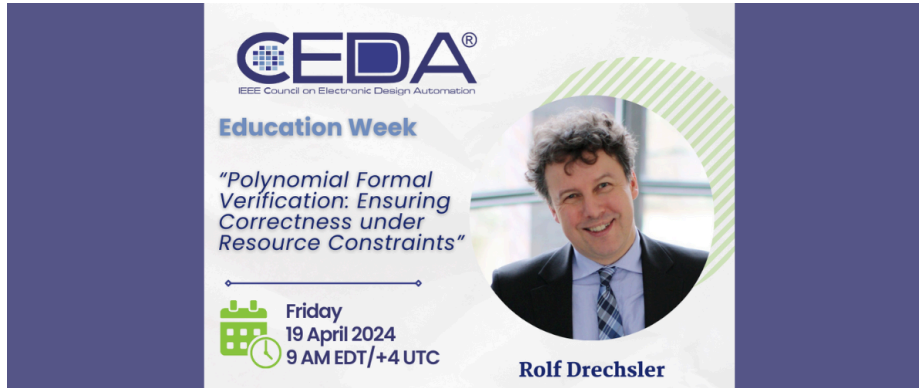- CAD For Emerging Technologies, Paradigms

**Learn More**



## IEEE Education Week with Dr. Qinru Qiu

Join CEDA for IEEE Education Week!

The featured speaker on **15 April 2024 at EDT 2 PM or UTC +4** is Dr. Qinru Qiu presenting her talk "A Journey into Neuromorphic Computing: Models, Algorithms, and Implementations."

**Registration**
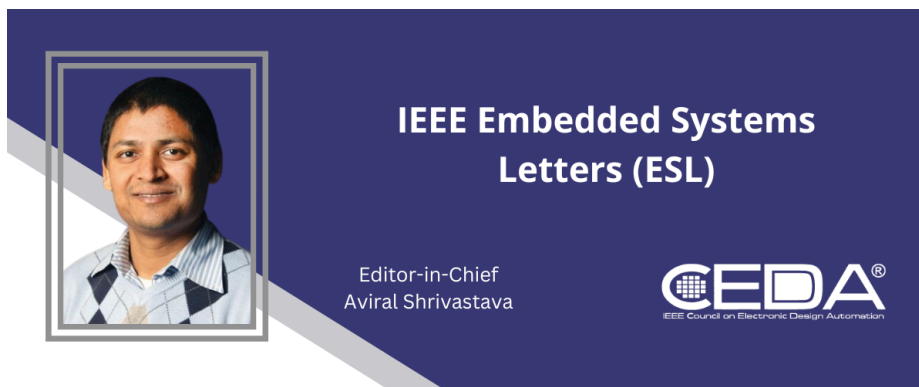


## IEEE Education Week with Rolf Drechsler

Join CEDA for IEEE Education Week!

The featured speaker on **19 April 2024 at EDT 9 AM or UTC +4** is Rolf Drechsler presenting his talk "Polynomial Formal Verification: Ensuring Correctness under Resource Constraints."

**Registration**



## IEEE Embedded Systems Letters (ESL)

We are thrilled to announce exciting changes at IEEE Embedded Systems Letters (ESL) tailored to enhance the experience of authors and better serve the embedded systems community.

Most importantly, we are streamlining the submission and expediting the review process. IEEE ESL will strive to achieve a one-month decision time.

This means that you can expect to receive a decision on your manuscript within one month of submission, significantly expediting the publication timeline and ensuring swift dissemination of your research findings.

IEEE ESL is already the best venue for publishing early research results in an easily digestible format. Our concise four-page paper format enables authors to succinctly present their most promising research findings, making IEEE ESL the ideal platform for sharing groundbreaking discoveries with the embedded systems research community. We do this while maintaining the highest standards of quality and rigor in our peer review process.

**Learn More**



## IEEE Design&Test

IEEE Design&Test has extended the deadline for paper submissions to the Special Issue on Wearable IoT Devices for Reliable Mobile Health Applications.

**Papers Due: 30 May 2024**

Topics:

- Mobile health applications
- Design optimization for wearable devices
- Methods to handle sensor data disturbances
- Missing data detection, imputation, and recovery Submission Guidelines
- Energy efficiency and quality of service optimization
- Privacy preserving mobile health applications
- Application-specific wearable IoT devices
- Reliability management and ageing in IoT devices

**Call For Papers**

## Safety and Security in Heterogeneous Open System-on-Chip Platforms Workshop (SSH-SOC 2024)

**23 June 2024 | San Francisco, CA, USA**

The Safety and Security in Heterogeneous Open System-on-Chip Platforms Workshop (SSH-SOC 2024) at the Design Automation Conference (**DAC 2024**) welcomes work-in-progress contributions and novel directions to tackle the challenges and profit from the opportunities provided by open hardware designs and architectures for the development of next-generation heterogeneous SoCs.

**Papers Due: 22 April 2024**

Topics:

- Security verification for hardware designs and system architectures
- Architectural aspects of secure system integration
- Secure system integration of third-party hardware components
- Automated firmware generation supporting secure system execution
- Security aspects of reconfigurable designs
- Time-predictable system execution in open-hardware designs
- Performance analysis, timing analysis, and worst-case analysis supporting time-predictable system execution and/or communications in open-hardware designs
- Automated firmware generation supporting time-predictable execution
- Fault tolerance and execution in harsh conditions leveraging open-hardware designs
- System architectures and methodologies supporting energy efficient/performant system execution in open-hardware designs
- Hardware/software co-design, co-integration and co-verification of open-source processors, accelerators, and components
- Open architectures for reconfigurable platforms and open CAD tools
- Tools and analysis for open FPGAs and reconfigurable platforms

**Workshop Website**

## International Conference on Synthesis, Modeling, Analysis and Simulation Methods, and Applications to Circuit Design (SMACD 2024)

**2-5 July 2024 | Volos, Greece**

The International Conference on Synthesis, Modeling, Analysis and Simulation Methods, and Applications to Circuit Design (SMACD 2024) is a forum devoted to modeling, simulation, and synthesis for Analog, Mixed-signal, RF (AMS/RF), and multi-domain (nanoelectronics, biological, MEMS, optoelectronics, etc.) integrated circuits and systems, as well as, emerging technologies and applications. Open-source tools and methods for IC design and experiences with modeling, simulation, and synthesis techniques in diverse application areas are also welcomed. Objective technologies include CMOS, beyond CMOS, and More-than-Moore such as MEMs, power devices, sensors, passives, etc.

**Conference Website**



## ACM/IEEE International Symposium on Machine Learning for CAD (MLCAD 2024)

**9-11 September 2024 | Snowbird, UT, USA**

The 6th ACM/IEEE International Symposium on Machine Learning for CAD (MLCAD 2024) is soliciting papers on aspects of applying ML to enhance CAD of electronic chips and systems.

**Papers Due: 18 May 2024**

Topics:

- Algorithms
- Tools
- Example applications
- Benchmarking
- Innovative solutions like Large Language Models for CAD (LLM-CAD)

**Symposium Website**

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## International Symposium on Formal Methods and Models for System Design (MEMOCODE 2024)

**3-4 October 2024 | Raleigh, NC, USA**

The 22nd International Symposium on Formal Methods and Models for System Design (MEMOCODE 2024) is soliciting research papers on formal methods in system design that address the foundations, engineering methods, tools, or experimental case studies.

**Abstracts Due: 6 May 2024**
**Papers Due: 20 May 2024**

Topics:

- Modeling Languages, Methods, and Tools
- Formal Methods and Tools
- Models and Methods for Developing Critical Systems
- Quantitative/Qualitative Reasoning
- Formal Methods/Models in Practice

## International Symposium on Industrial Embedded Systems (SIES 2024)

**23-25 October 2024 | Chengdu, China**

The 14th International Symposium on Industrial Embedded Systems (SIES 2024) is soliciting papers on embedded systems and their applications in a variety of industrial environments.

**Papers Due: 11 June 2024**

Topics:

- Embedded Systems
- System-on-Chip and Network-on-Chip Design & Testing
- Networked Embedded Systems and Edge Computing
- Embedded Applications

## Conferences

Design Automation Conference (**DAC 2024**)
🗓 23-27 June 2024
📍 San Francisco, CA, USA

Embedded Systems Week (**ESWEEK 2024**)
🗓 29 September-4 October 2024
📍 Raleigh, NC, USA

2024 ACM/IEEE International Conference on Computer-Aided Design (**ICCAD 2024**)

📅 27-31 October 2024

📍 New Jersey, USA

Asia and South Pacific Design Automation Conference (**ASP-DAC 2025**)

📅 20-23 January 2025

📍 Tokyo, Japan

Contact IEEE CEDA VP of Conferences Tsung-Yi Ho for sponsorship opportunities at **vp.conferences@ieee-ceda.org**.

## Publications

IEEE CEDA financially sponsors and co-sponsors several publications and publishes its *Currents* newsletter to inform the EDA community on industry news and research results.

Visit the individual publication pages for more information on publication scope, call for papers, and more.

### Top Accessed Articles in March 2024 (*as of 12 April 2024)

*IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems*

- **ViA: A Novel Vision-Transformer Accelerator Based on FPGA**
- **TrueNorth: Design and Tool Flow of a 65 mW 1 Million Neuron Programmable Neurosynaptic Chip**
- **NeuroSim: A Circuit-Level Macro Model for Benchmarking Neuro-Inspired Architectures in Online Learning**

*IEEE Design&Test*

- **Furthering Moore's Law Integration Benefits in the Chiplet Era**
- **High-Bandwidth Memory (HBM) Test Challenges and Solution**
- **Machine Learning in Advanced IC Design: A Methodological Survey**

### IEEE Embedded Systems Letters

- **An AI-Based Ventilation KPI Using Embedded IoT Devices**
- **Three-Stage Power Supply System Model for a Wearable IoT Device for COVID-19 Patients**
- **Embedded Systems Education: Experiences With Application-Driven Pedagogy**

Contact IEEE CEDA VP of Publications Jörg Henkel at **henkel@kit.edu** or the journal's respective EiC for questions regarding CEDA-sponsored publications.

## Share what's new

We thank you for forwarding this content to others who might be interested including other members of your group or organization.